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#### **Graphics Processor Units (GPUs)**

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### Acronyms

Acronym	Definition							
BOK	Body of Knowledge (document)							
CUDA	Compute Unified Device Architecture							
DUT	Device Under Test							
GPGPU	General Purpose Graphics Processing Unit							
GPU	Graphics Processing Unit							
MBU	Multi-Bit Upset							
MGH	Massachusetts General Hospital							
NEPP	NASA Electronic Parts and Packaging							
PTX	Parallel Thread Execution							
RTOS	Real Time Operating System							
SBU	Single-Bit Upset							
SEE	Single Event Effect							
SEFI	Single Event Functional Interrupt							
SEU	Single Event Upset							
SIMD	Single Instruction Multiple Data							
SoC	System on Chip							
TID	Total Ionizing Dose							



## Outline

- What the technology is (and isn't)
- Our tasks and their purpose
  - The setup around the test setup
  - Parametric considerations
  - Lessons learned
- Collaborations
  - Roadmap
  - Partners
  - Results to date
  - Plans
- Comments



## Technology

- Graphics Processing Units (GPU) & General Purpose Graphics Processing Units (GPGPU) are considered compute devices that behave like coprocessors
  - Take assignments from another device
  - Inability to load and execute code on boot by itself
- Using high-level languages, GPU-accelerated applications run the sequential part of their workload on the CPU – which is optimized for single-threaded performance – while accelerating parallel processing on the GPU.



#### Purpose

- GPUs are best used for single instructionmultiple data (SIMD) parallelism
  - Perfect for breaking apart a large data set into smaller pieces and processing those pieces in parallel
- Key computation pieces of mission applications can be computed using this technique
  - Sensor and science instrument input
  - Object tracking and obstacle identification
  - Algorithm convergence (neural network)
  - Image processing
  - Data compression algorithms



## **Device Selection**

 Unfortunately, GPUs come in multiple types, acting as primary processor (SoC) and coprocessor (GPU)



#### Nvidia TX1 SoC







#### **Intel Skylake Processor**





## **Device Software**

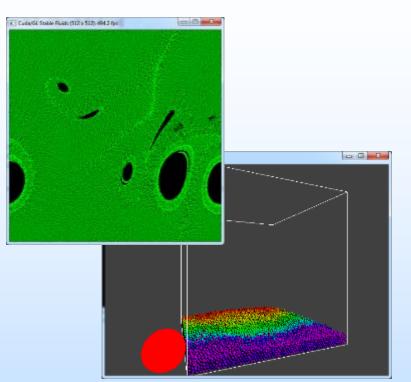
- Does it need its own operating system?
  - E.g. Linux, Android, RTOS
- Can we just push code at it?
  - E.g. Assembly, PTX, C
- Payload normalization
  - Can we run the same code on the previous generation and next generation of the device?
  - Cannot with CUDA code; can with OpenCL

Real-time Operating System (RTOS) Parallel Thread Execution (PTX) CUDA is a parallel computing platform and application programming interface (API) model created by Nvidia



## **Payloads**

- Visual Simulations
  - Sample code
  - Fuzzy Donut (i.e. Furmark)
- Sensor streams
  - Camera feed
  - Offline video feed
- Computational loading
  - Scientific computing models
- Easy Math
  - 0 + 0 … wait … should = 0





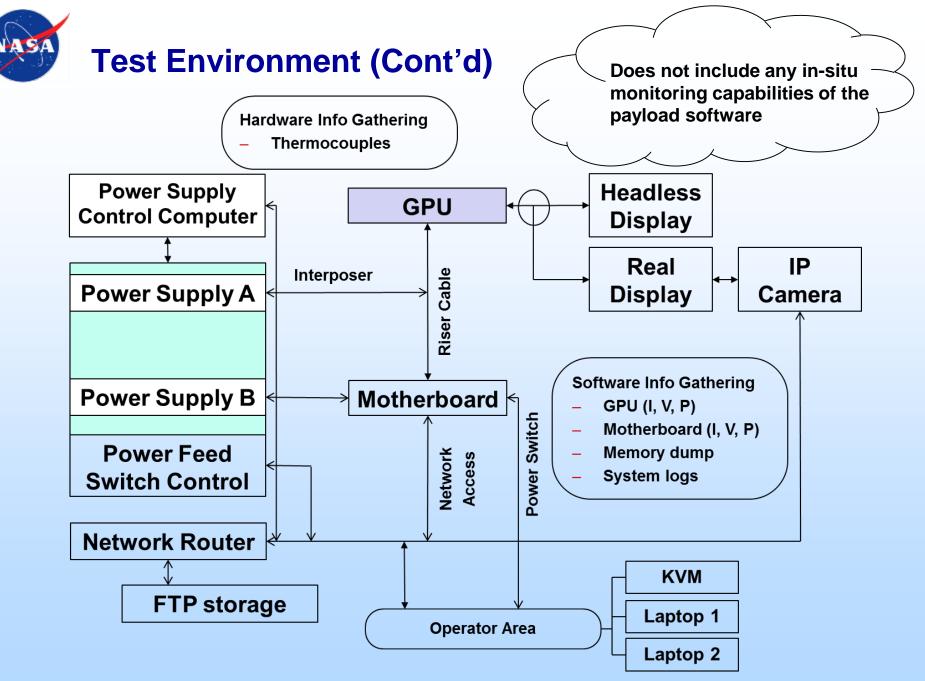
### **Test Setup**

- Things to consider in the test environment
  - Operating system daemons
  - Location of payload and results
  - Data paths upstream/downstream
  - Control of electrical sources
  - Temperature control (i.e. heaters) in a vacuum
- Things to consider in the DUT
  - Is the die accessible?
  - What functional blocks are accessible?
  - Which functions are independent of each other?
  - Does it have proprietary or open software?



## **Test Environment**

- Beam line
  - DUT testing zone where collateral damage can happen
  - Shielding for everything non-DUT
- Operator Area
  - Cables, interconnects and extenders
  - Signal integrity at a distance
  - "Everything that was done in a lab, in front of you on a bench, now must be done from a distance..."



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## **Test Environment (Cont'd)**



**Tripod and mounting** 

**External power** 

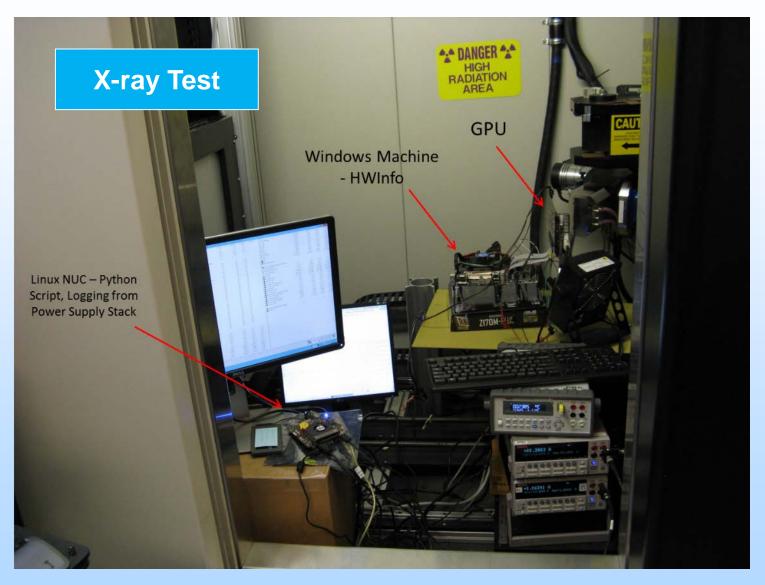
**Power injection** 

#### Arrows and circle mark locations of the lead and acrylic block fortresses

Pictures are from Massachusetts General Hospital Francis Burr Proton Facility



## **Test Environment (Cont'd)**



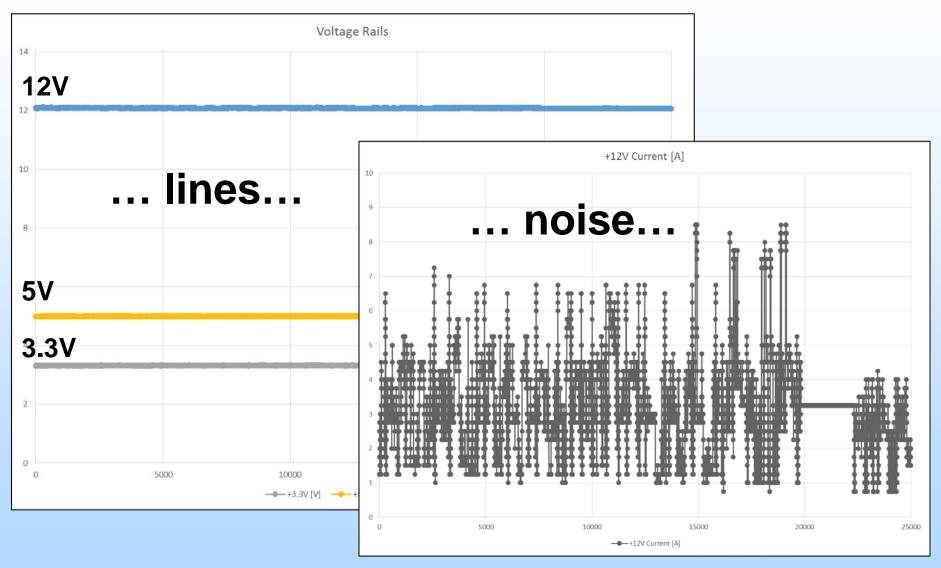


## **DUT Health Status**

- Accessible nodes
  - Network
    - Heart beat by inbound ping
    - Heart beat by timestamp upload
  - Peripherals response
    - "Num lock"
  - Visual check
    - Remote
    - Local
    - Local with remote viewing
  - Electrical states
    - At the system
    - At the DUT



## **Monitoring Data**

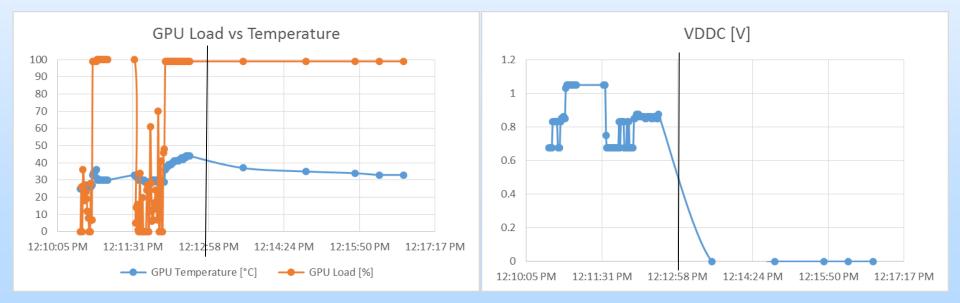


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# Monitoring Data (Cont'd)

- Significant digits are important
- Resolution is needed for correlation
  - Faster sampling speed
  - Smaller units (µV or mV, not Volts)





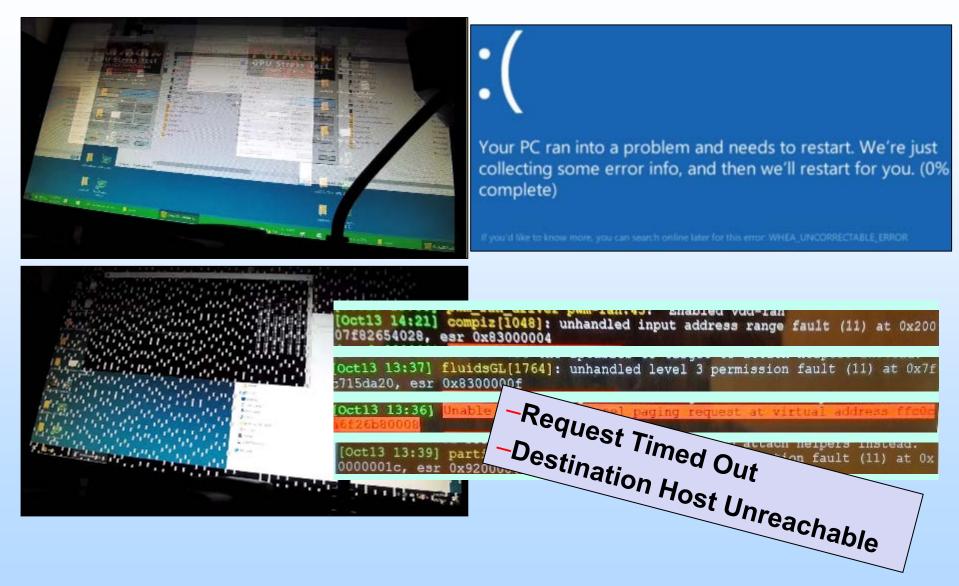
# Monitoring Data (Cont'd)

#### • Even better (albeit being a mock up):

ontinuous Po	ower Supply I	Monitor Rev 1	.0-rel EXIT	Ch1 800m-	635.501m	LOGGING	ŝ.
S Type Simulation	Save Settings	Reset	Leave Pwr ON After Latch?	Mon 600m- En Latch 1 400m-			Por
SET	Recall Settings	Status?	Master Latch Control	Latch 1 200m-	$\sim$	10-25-20 Heat Mo	OF
HANNEL 1	CHANNEL 2	CHANNEL 3	CHANNEL 4			19:25:29 Heat Mo	ON
Voltage (V)	Voltage (V)	Voltage (V)	Voltage (V)	Ch 2 1- Mon 750m- En Latch 2 500m-	633.372m	3	OFF
OVP (V)	OVP (V)	OVP (V)	OVP (V)	Latch 2 250m-			_
Current Limit (A)	Current Limit (A)	Current Limit (A)	Current Limit (A)	0-		19:25:28	
0CP	1 OCP	0CP	1 OCP	Ch3 1-			
Disable	Disable	Disable	Disable	800m - Mon 600m -	414.803m	Digita	al IO
OCP Delay	OCP Delay	OCP Delay	OCP Delay	En Latch 3 400m -		1	
	90001		[ grown	Latch 3 200m- 0- 19-25-24	$\sim$	2	2
DUT	CH 2 OUT	CH 3 OUT	CH 4 OUT			19:25:29	5
				Ch 4 0 100u-	0.000	5 6	5
EN 1	EN 2	EN 3	EN 4	Mon -200m- En Latch 4 -500m-		6	
ALLO			ALL OFF	Latch 4 -750m-		7 6	
				-1-		19:00:05 Beam Cor	



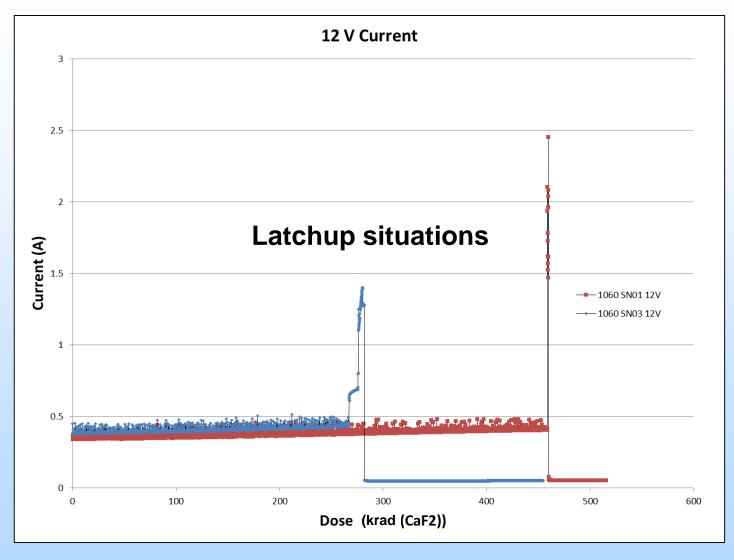
## What does a failure look like?



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## Failures (Cont'd)





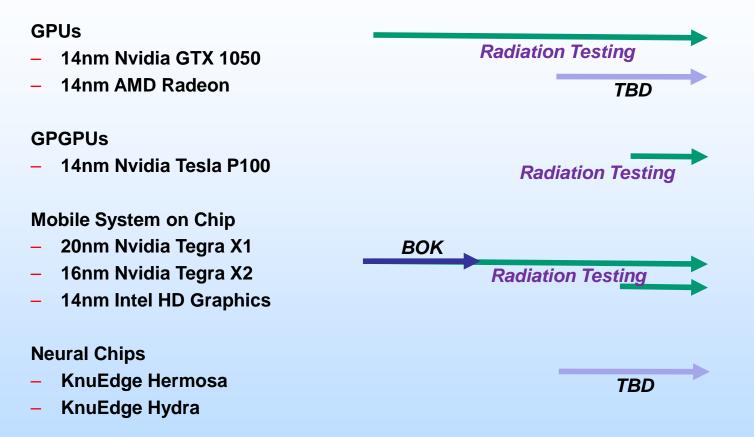
## **Learning Experience**

- Every test is another learning experience
  - "Is the laser alignment jig in the beam path..."
  - Nuances with controllable nodes
    - DUT power switch
    - Remote power sources
    - DUT electrical isolation from test platform
    - Thermal paths
  - Improvements are always possible, but preparation time may not be as abundant
  - Prioritization during development is important
    - Software payload
    - Hardware monitoring
    - Remote troubleshooting capabilities



## **GPU Roadmap**

- collaborative with NSWC Crane, others



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#### **Partners**

- Navy Crane
  - Conducting testing on Nvidia 14nm GPUs
- Collaboration with partners is yielding a comprehensive test suite
  - L1 and L2 cache
  - Registers
  - Shared, Internal, Texture and Global memory
  - Control logic



## **Qualification Guidance**

#### - Creation of GPU Body of Knowledge (BoK) document

- Technology
  - Silicon
  - Packaging
  - Heterogeneous constituents
- Reliability
  - Semiconductor mechanisms
  - Package issues
  - Scaling issues
- Failure categories and trends
- Software & Hardware sources

#### Future guidelines will be developed for this technology to include qualification and test methods



## **Results to Date**

- Developing software for cross platform use
  - Nvidia Tegra X SoC ARM with embedded Linux
  - Nvidia GPUs GPU for x86 Windows and Linux
  - Intel Skylake Processor IP Block for x86 Linux
  - Qualcomm Adreno & Mali GPU IP Block for ARM Linux
- Proton test result ranges are dependent on physical target within DUT
  - Cross section (σ, cm<sup>2</sup>): 1x10<sup>-7</sup> to 9x10<sup>-9</sup>
  - Flux (p/cm<sup>2</sup>/sec): 1x10<sup>6</sup> to 7x10<sup>6</sup>



# Plans (w Schedule)

- More proton testing on 14nm GPUs
  - Test OpenCL payloads
  - Test L1, L2, registers, shared memory & control logic
  - Record die temperature, 12V and 3.3V rail voltages and currents, system events (and observations)
- Two proton test sessions and significant in-lab work has permitted improvements to:
  - Thermal-electrical monitoring of the DUTs though some more improvements are necessary to achieve the desired resolution
  - Proving out which code libraries won't work for the type of testing we're conducting



## FY17-18: GPU Testing

		_	_	_	_	_	_	_	_		_				
Description:											FY17-18 Plans:				
<ul> <li>This is a task over all device topologies and process</li> <li>The intent is to determine inherent radiation tolerance and sensitivities</li> <li>Identify challenges for future radiation hardening efforts</li> <li>Investigate new failure modes and effects</li> <li>Testing includes total dose, single event (proton) and reliability Test vehicles will include a GPU devices from nVidia and other vendors as available         <ul> <li>Compare to previous generations</li> <li>Investigate failure modes/compensation for increased power consumption</li> </ul> </li> </ul>												her	<ul> <li>Continue development of universal test suite</li> <li>Probable test structures for SEE: <ul> <li>Nvidia (16, 14, 10nm)</li> <li>AMD (14nm)</li> <li>Intel (14nm)</li> </ul> </li> <li>Tests: <ul> <li>characterization pre, during and post-rad</li> </ul> </li> </ul>		
Schedule:													Deliverables:		
Microelectronics	FY17 FY18						FY1	18				<ul> <li>Test reports and quarterly reports</li> </ul>			
T&E	М	J	J	Α	S	0	Ν	D	J	F	М	Α	<ul> <li>Expected submissions for publications</li> </ul>		
On-going discussions for test samples															
GPU Test Development		$\diamond$	>												
SEE Testing													NASA and Non-NASA Organizations/Procurements:		
Analysis and Comparison												$\diamond$	<ul> <li>Source procurements: Proton (MGH), TID (GSFC)</li> </ul>		

#### Pls: GSFC/Lentech/Wyrwas

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### Conclusion

- NEPP and its partners have conducted proton, neutron and heavy ion testing on several devices
  - Have captured SEUs (SBU & MBU),
  - Have seen traceable current spikes,
  - But predominately have encountered system-based SEFIs
- GPU testing requires a complex platform to arbitrate the test vectors, monitor the DUT (in multiple ways) and record data
  - None of these should require the DUT itself to reliably perform a task outside of being exercised
- Progress has been made in proving out multiple ways to simulate and enumerate activity on the DUT
  - Narrowing down on a universal test bench
  - End goal is to make test code platform independent



## Acknowledgement

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